

RELIABILITY REPORT
FOR
ICM7218AIQI+
PLASTIC ENCAPSULATED DEVICES

November 3, 2014

MAXIM INTEGRATED

160 RIO ROBLES
SAN JOSE, CA 95134

Approved by
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Conclusion

The ICM7218AIQI+ successfully meets the quality and reliability standards required of all Maxim Integrated products. In addition, Maxim Integrated's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim Integrated's quality and reliability standards.

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I. Device Description

A. General

The Maxim ICM7218 display driver interfaces microprocessors to an 8 digit, 7 segment, numeric LED display. Included on chip are two types of 7 segment decoders, multiplex scan circuitry, segment and digit drivers, and an 8 x 8 static memory. The ICM7218A and ICM7218B accept data in a serial format and drive common anode (ICM7218A) or common cathode (ICM7218B) displays. The ICM7218C and ICM7218D accept data in a parallel format and drive common anode (ICM7218C) or common cathode (ICM7218D) displays. All four versions can display the data in either hexadecimal or code B format. The ICM7218A and ICM7218B also feature a No Decode mode where each individual segment can be independently controlled. This is particularly useful in driving bar graphs. The Maxim ICM7218 is an alternative for both the Intersil ICM7218 and ICM7228. When ordering, specify ICM7218 for both devices.

II. Manufacturing Information

A. Description/Function:	8-Digit, Multiplexed, LED Decoder Driver
B. Process:	M6
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Philippines
F. Date of Initial Production:	Pre 1997

III. Packaging Information

A. Package Type:	28-pin PLCC
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-0501-0038
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	95°C/W
K. Single Layer Theta Jc:	25°C/W
L. Multi Layer Theta Ja:	N/A
M. Multi Layer Theta Jc:	N/A

IV. Die Information

A. Dimensions:	111X151 mils
B. Passivation:	Si ₃ N ₄ /SiO ₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/1.0%Si
D. Backside Metallization:	None
E. Minimum Metal Width:	Metal1 = 0.5 microns (as drawn)
F. Minimum Metal Spacing:	Metal1 = 0.45 microns (as drawn)
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO ₂
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

- A. Quality Assurance Contacts: Don Lipps (Manager, Reliability Engineering)
Bryan Preeshl (Vice President of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% for all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 160 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 6.87 \times 10^{-9}$$

$\lambda = 6.87$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim Integrated's reliability monitor program. Maxim Integrated performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maximintegrated.com/qa/reliability/monitor>. Cumulative monitor data for the M6 Process results in a FIT Rate of 0.10 @ 25C and 1.74 @ 55C (0.8 eV, 60% UCL).

B. E.S.D. and Latch-Up Testing (ESD lot NDDDDO023A D/C9617, Latch-Up lot XDDAAE122A D/C 9411)

The DD04 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2000V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-100mA.

Table 1
Reliability Evaluation Test Results

ICM7218AIQI+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)	Ta = 135°C	DC Parameters	80	0	NDDCDZ010A
	Biased	& functionality	80	0	NDDBDZ006A
	Time = 192 hrs.				

Note 1: Life Test Data may represent plastic DIP qualification lots.